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'APPLICATION NO. CO		057	class 34	ART UNIT	EXAMI	NER	ARC				
Jozef Puymbroeck Substrate with at least two metallized polymer bumps for soldered connection to wiring											
ISSUING CLASSIFICATION											
ORIGINAL	CROSS REFERENCE(S)										
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TERMINAL		DRAWINGS		CLAIMS ALLOWED		
L_J DISCLAIMER	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
☐ The term of this patent				NOTICE OF ALI	LOWANCE MAILED	
subsequent to (date) has been disclaimed.	(Assistant	Examiner)	(Date)			
The term of this patent shall not extend beyond the expiration date						
of U.S Patent. No.				ISSUE FEE		
				Amount Due	Date Paid	
	(Primary I	Examiner)	(Date)			
☐ The terminalmonths of this patent have been disclaimed	(Legal Instrum	ents Examinar)	(Date)	ISSUE BA	TCH NUMBER	
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The information disclosed herein may be res Possession outside the U.S. Patent & Traden					35, Sections 122, 181 and 36	
orm PTO-436A Rev. 6/99)			FILED WITH:	_ ` ' \	FICHE CD-RC	

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